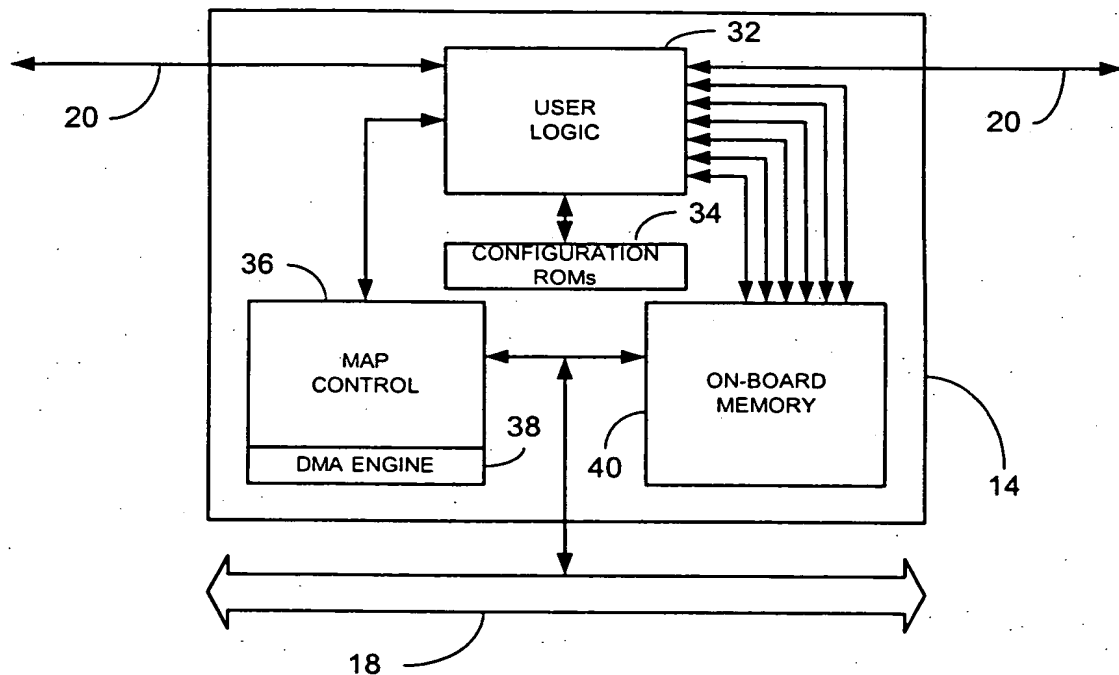
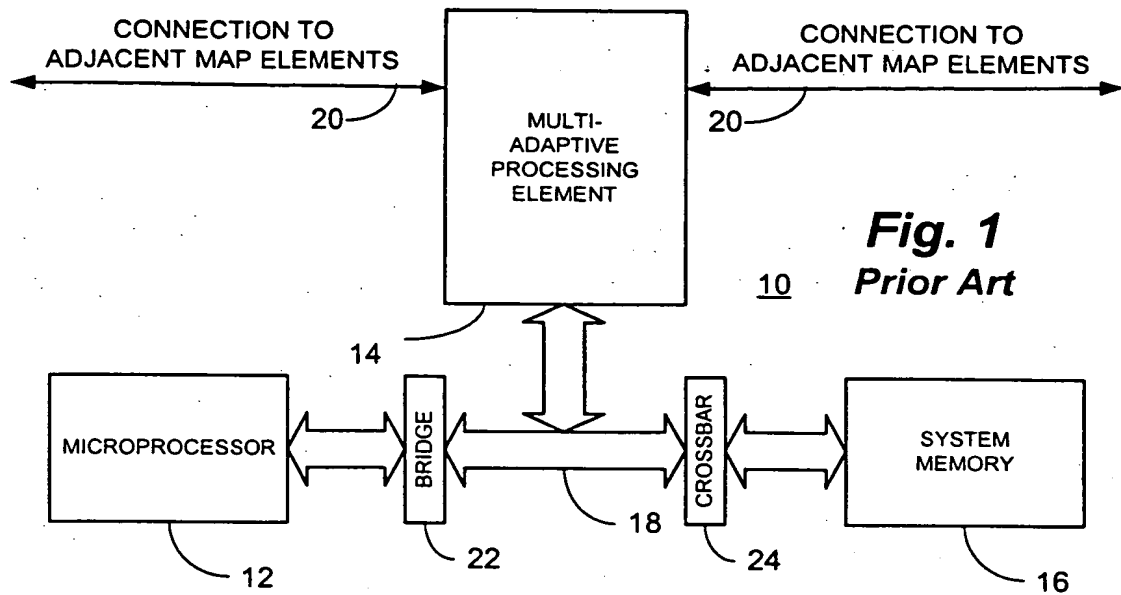


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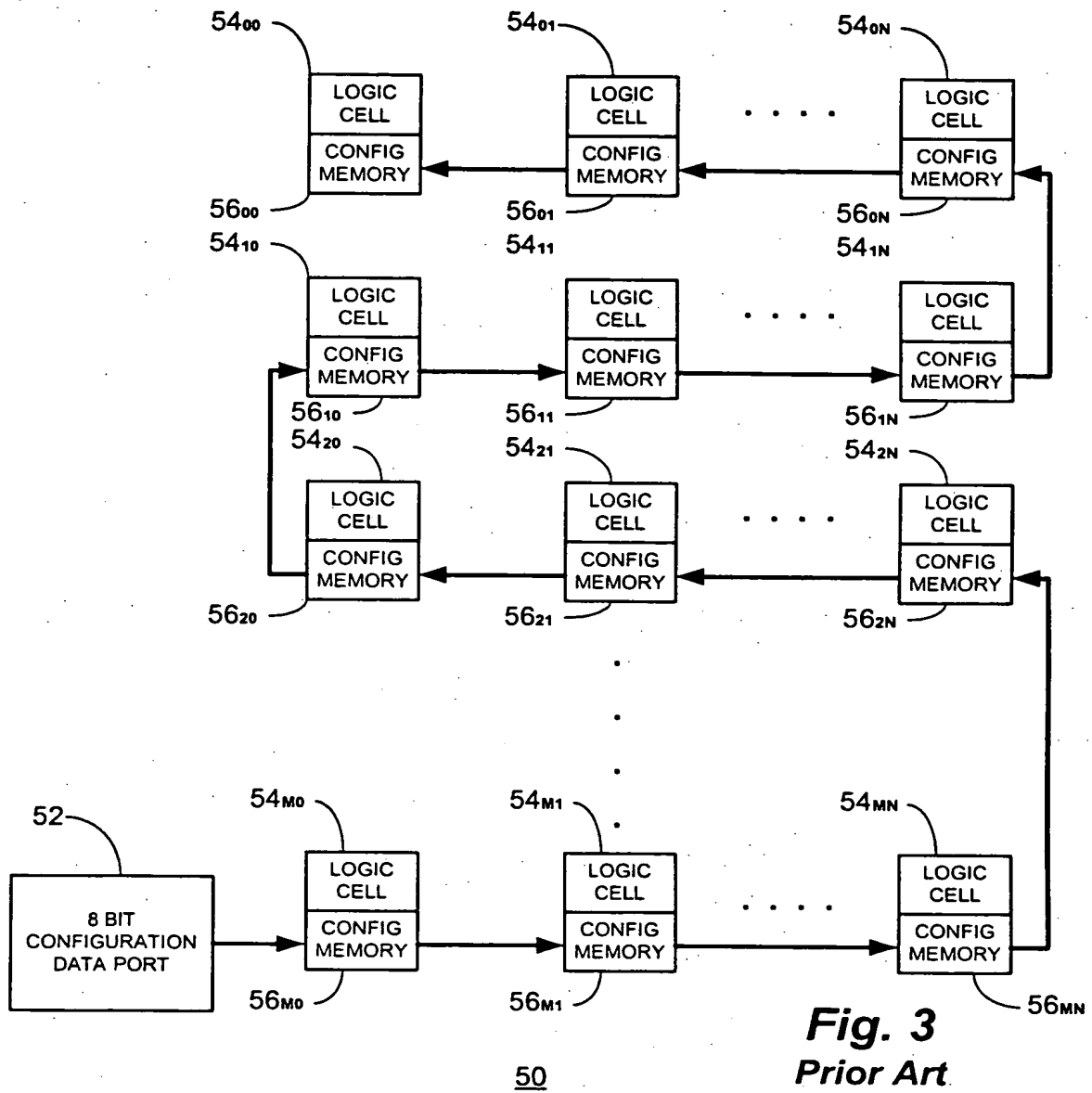
1/4



**Fig. 2**  
Prior Art

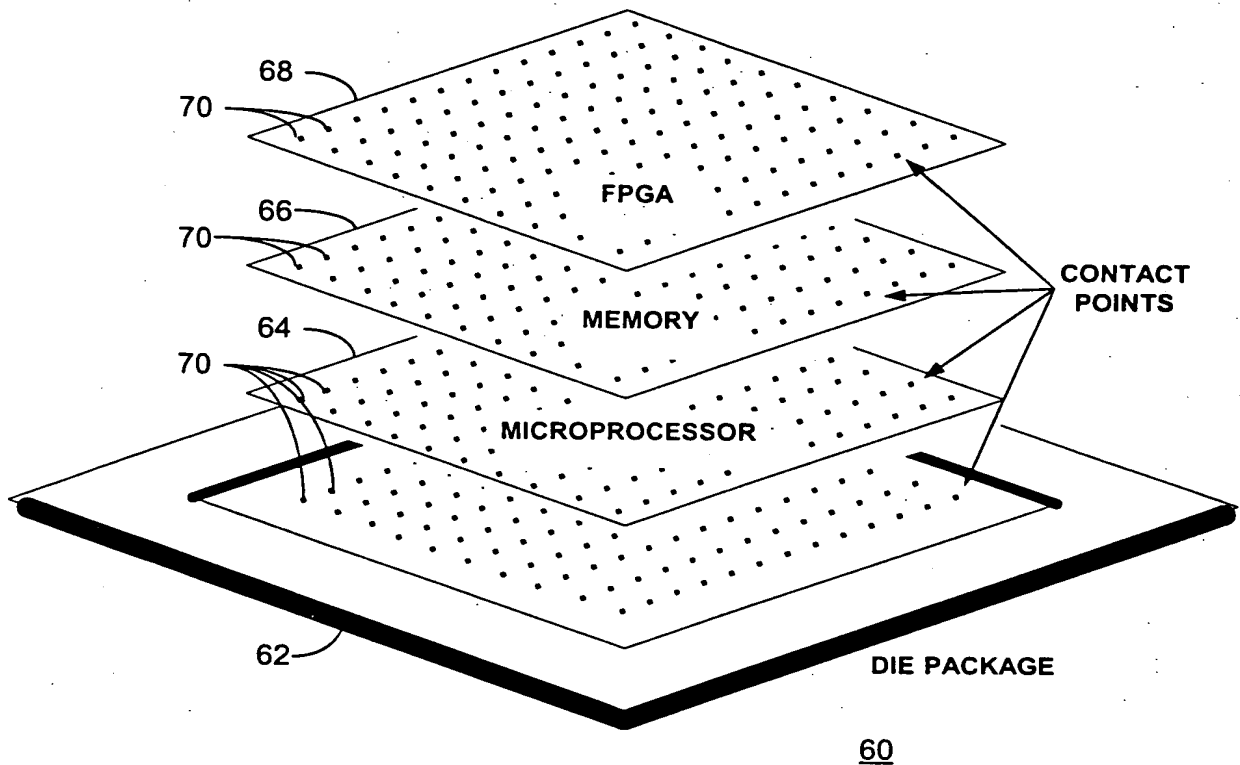
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**Fig. 4**

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4/4

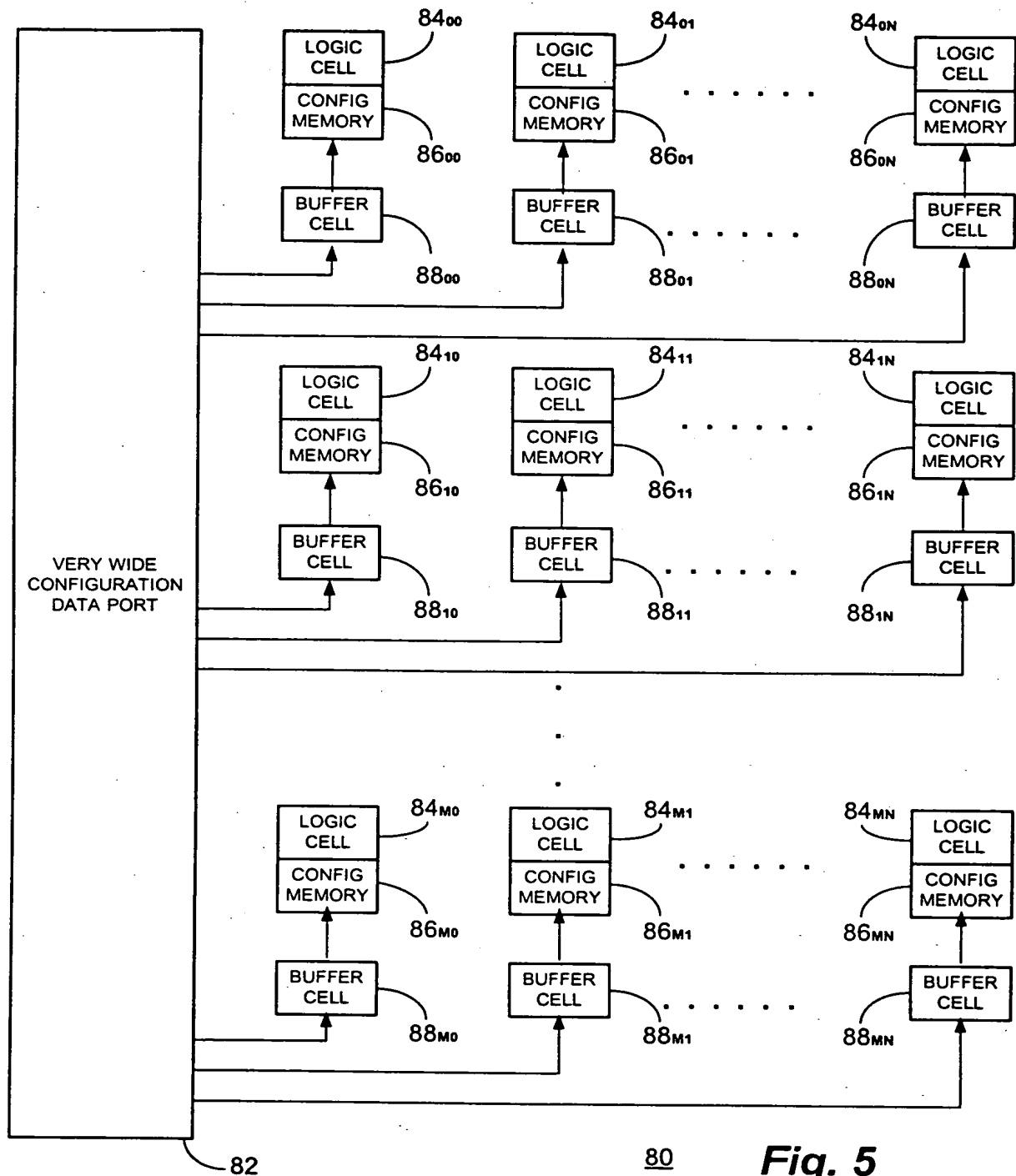


Fig. 5

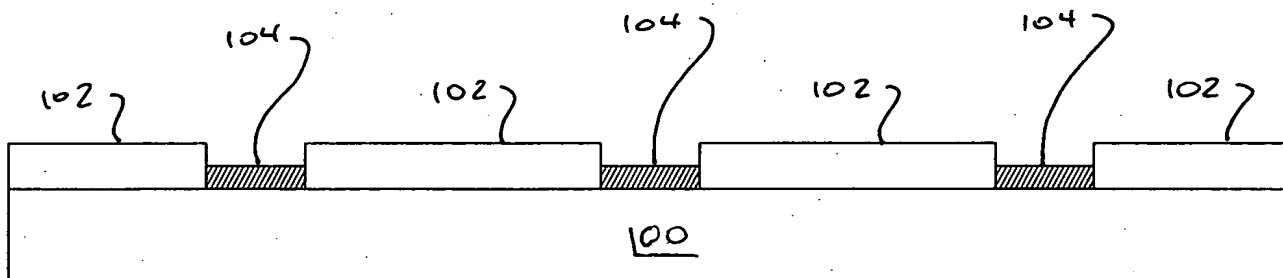


FIG. 6

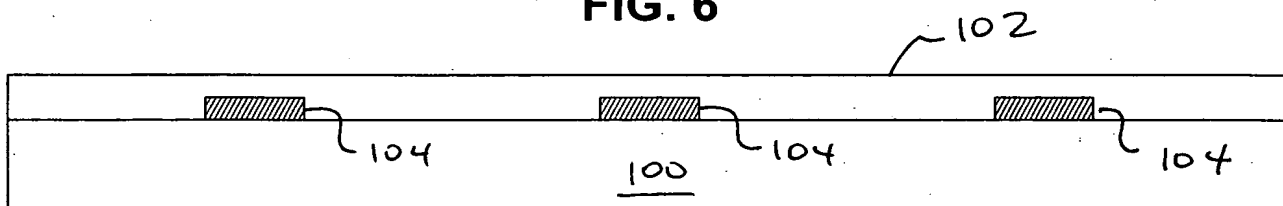


FIG. 7

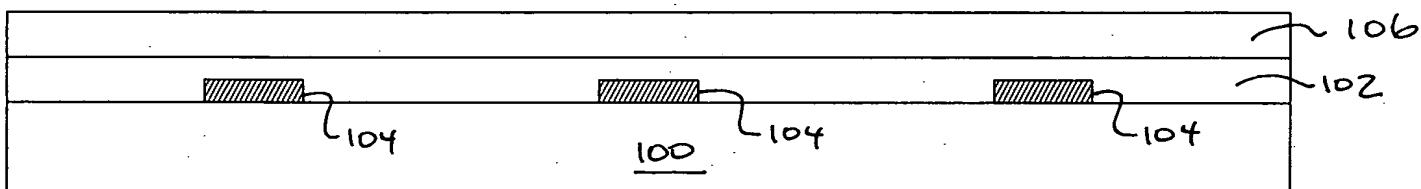


FIG. 8

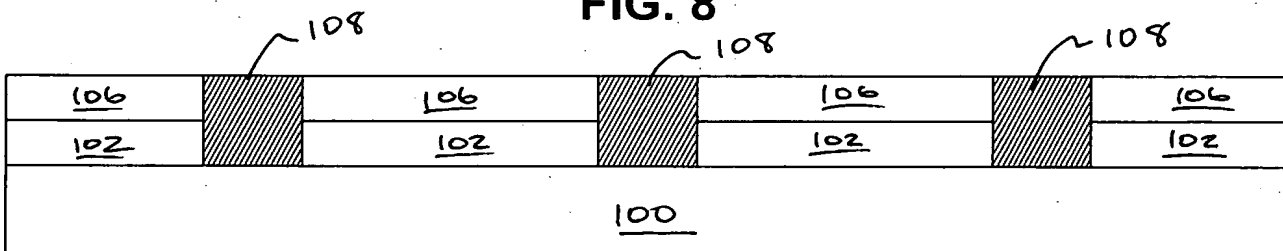


FIG. 9

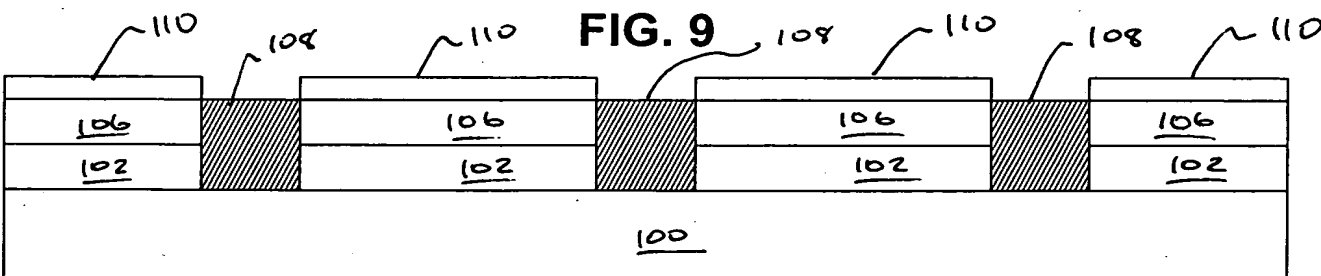


FIG. 10

S/N: -----  
Docket No.: ARB001 CONCIP  
Title: RECONFIGURABLE PROCESSOR MODULE  
COMPRISING HYBRID STACKED INTEGRATED  
CIRCUIT DIE ELEMENTS  
Inv: Jon M. Huppenthal & D. James Guzy

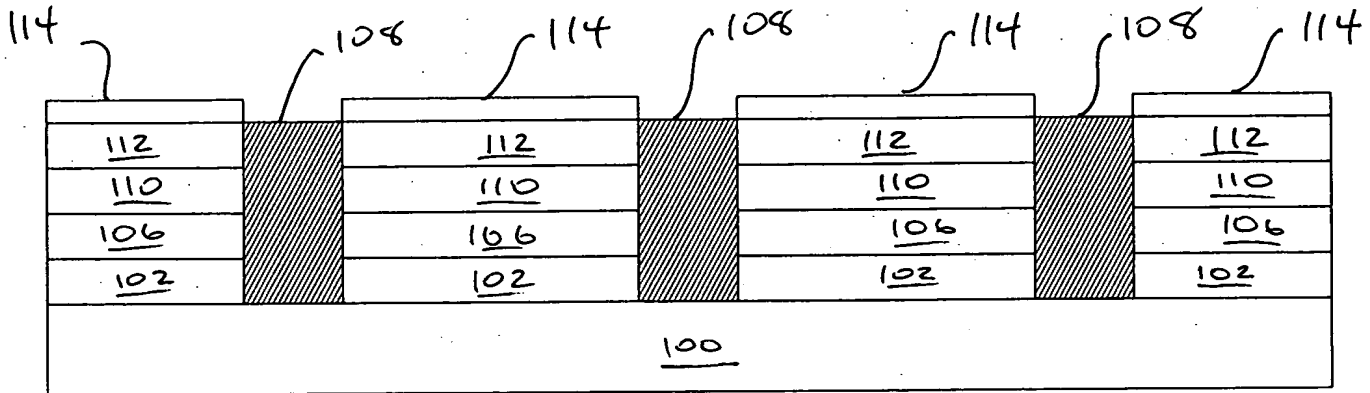


FIG. 11